



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31B225KOH4PNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 2.2 µF, 16V, ±10%, X7R, 1206

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>31</u> <u>B</u> <u>225</u> <u>K</u> <u>O</u> <u>H</u> <u>4</u> <u>P</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor						
2	Size	1206 (inch code)	L: 3	3.2 ± 0.2	mm	W:	1.6 ± 0.2	mm
3	Dielectric	X7R	(3) Inner (electrode		Ni	
4	Capacitance	2.2 μF		Termi	nation		Cu , Ag-epoxy	
⑤	Capacitance	±10 %		Plating	g		Sn 100%	(Pb Free)
	tolerance		(Produ	ct		Automotive	
6	Rated Voltage	16 V	(1	Grade	code		Standard	
7	Thickness	1.6 ± 0.2 mm	Œ	① Packa	ging		Embossed Type	e. 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition				
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C				
Exposure	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion				
	Tan δ : 0.05 max					
IR : More than 10,000⋒ or 500⋒∨∠/F						
	Whichever is Smaller					
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles				
	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion				
	Tan δ : 0.05 max	1 cycle condition :				
	IR : More than 10,000⋒Ω or 500⋒Ω× <i>μ</i> F	-55+0/-3℃(15±3min) -> Room Temp(1min.)				
	Whichever is Smaller	-> 125+3/-0 ℃ (15±3min) -> Room Temp(1min.)				
Destructive Physical No Defects or abnormalities		Per EIA 469				
Analysis						
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle				
	Capacitance Change : Within ±12.5%	Heat (25~65℃) and humidity (80~98%), Unpowered				
	Tan δ : 0.05 max	measurement at 24±2hrs after test conclusion				
	IR : More than 10,000⋒Ω or 500⋒Ω×μF					
	Whichever is Smaller					
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85℃/85%RH, Rated Voltate and 1.3~1.5V,				
	Capacitance Change : Within ±12.5%	Add 100kohm resistor				
	Tan δ : 0.05 max	Measurement at 24±2hrs after test conclusion				
	IR : More than 500MΩ or 25MΩ×μF	The charge/discharge current is less than 50mA.				
	Whichever is Smaller					
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125℃, 200% Rated Voltage,				
Operating Life	Capacitance Change : Within ±12.5%	Measurement at 24±2hrs after test conclusion				
	Tan δ : 0.05 max	The charge/discharge current is less than 50mA.				
	IR : More than 1000MΩ or 50MΩ×μF					
	Whichever is Smaller					

	Performance	Test condition				
External Visual No abnormal exterior appearance		Microscope ('10)				
Physical Dimensions Within the specified dimensions		Using The calipers				
Mechanical ShockAppearance : No abnormal exterior appearanceCapacitance Change : Within ±10%Tan δ, IR : initial spec.		Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) Peakvalue Duration Wave Velocity 1,500G 0.5ms Half sine 4.7m/sec.				
Vibration	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"×5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000Hz.				
Resistance to Solder Heat	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	Solder pot : 260±5℃, 10±1sec.				
Thermal Shock	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	-55℃/+125℃. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air				
ESD	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	AEC-Q200-002				
Solderability	95% of the terminations is to be soldered evenly and continuously	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5°C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5°C solder: a solution ethanol and rosin				
Electrical Characterization	Capacitance: Within specified tolerance Tan δ (DF): 0.035 max. IR(25°C): More than 10,000μΩ or 500μΩ×μF IR(125°C): More than1,000μΩ or 10μΩ×μF Whichever is Smaller Dielectric Strength	The Capacitance /D.F. should be measured at 25°C, 1½±10%, 1.0±0.2Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25°C, @125°C for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds				
Board Flex	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10%	Bending to the limit (2mm) for 5 seconds				
Terminal Strength(SMD)	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10%	18N, for 60±1 sec.				
Beam Load	Destruction value should not be exceed Chip Length ≥ 3.2mm a) Chip Thickness < 1.25mm : 15N b) Chip Thickness ≥ 1.25mm : 54.5N	Beam speed 2.5±0.25mm/sec				
Temperature X7R Characterisitcs (From -55 °C to 125 °C, Capacitance change show		ud be within ±15%)				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\text{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.